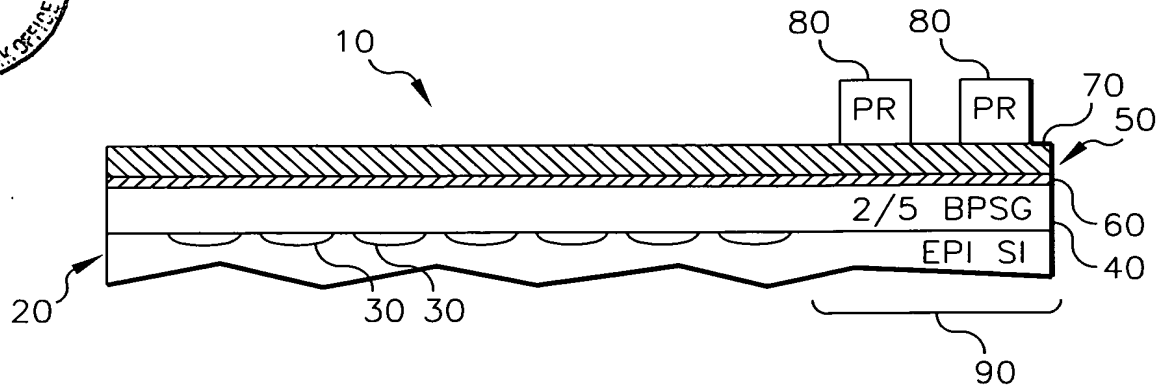


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A cross-sectional view of a semiconductor device. The device consists of a substrate 20 with a wavy bottom surface. A thin layer 30 is formed on the substrate 20. A middle layer 60 is formed on the thin layer 30. A top layer 50 is formed on the middle layer 60. Two resist patterns 80 are formed on the top layer 50. Each resist pattern 80 includes a photoresist layer 70 and a protective layer 80.

FIG. 3

METHOD FOR FORMING LIGHT SHIELD PROCESS FOR SOLID-STATE IMAGE SENSOR WITH MULTI-METALLIZATION LAYER (AMENDED)

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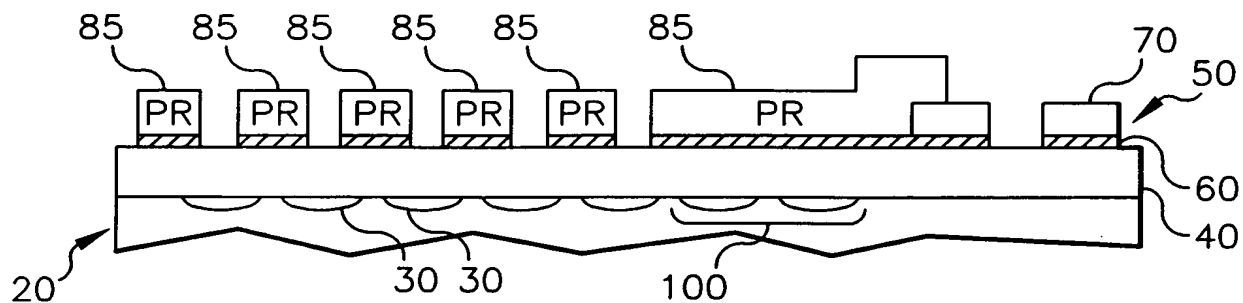


FIG. 4

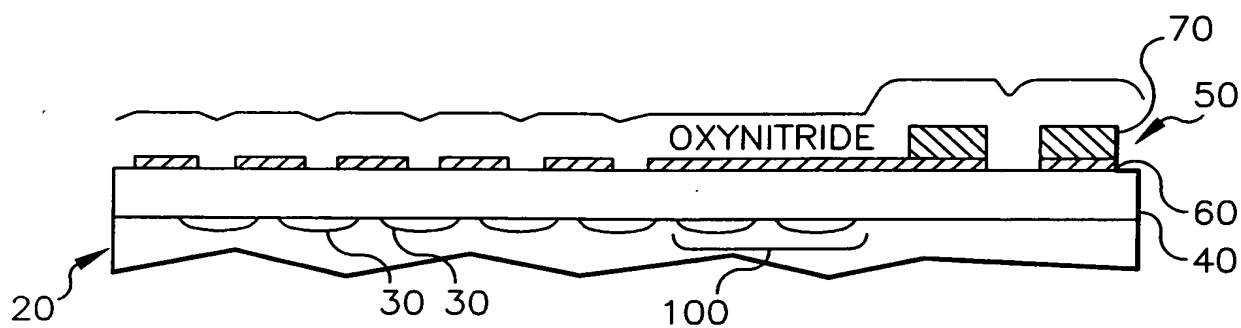


FIG. 5